

WHAT IS CLAIMED IS:

1. A flexible wiring board having:
a first resin film;
a first wiring film, a bottom face of which is embedded into the first resin film;
and
a second wiring film, a bottom face of which is in contact with a surface of the first resin film.
2. The flexible wiring board as claimed in claim 1, wherein a surface of the first wiring film is flush with a surface of the second wiring film.
3. The flexible wiring board as claimed in claim 1, wherein a second resin film is formed on the surfaces of the first and second wiring films.
4. The flexible wiring board as claimed in claim 3, wherein at least one first opening is formed in the part of the second resin film where the first wiring film is disposed.
5. The flexible wiring board as claimed in claim 3, wherein at least one second opening is formed in a part of the second resin film where the second wiring film is disposed.
6. The flexible wiring board as claimed in claim 1, wherein at least one third opening is formed in a part of the first resin film where the first wiring film is disposed.
7. The flexible wiring board as claimed in claim 4, wherein a metal bump is located in at least one of the first openings.
8. The flexible wiring board as claimed in claim 5, wherein a metal bump is located in at least one of the second openings.
9. The flexible wiring board as claimed in claim 6, wherein a metal bump is located in at least one of the third openings.
10. The flexible wiring board as claimed in claim 1, wherein the first resin film has a flat surface at an opposite side to where the first and second wiring film are disposed.
11. The intermediate product of a flexible wiring board having a first resin film, and a metal foil wherein the metal foil has a thin film part and a thick film part connecting to the thin film part,
the thick film part has a larger thickness than a thickness of the thin film part
and is connected to the thin film part,
a surface of the metal foil is flush,

a part of a bottom face of the metal foil, where the thick film part is disposed, is embedded into the first resin film,

a part of the bottom face of the metal foil, where the thin film part is disposed, is in contact with a surface of the first resin film, and

the first resin film has a flat surface in an opposite side to where the metal foil is disposed.

12. A multi-layer flexible wiring board comprising a first flexible wiring board and a second flexible wiring board connecting each other, wherein

the first flexible wiring board having:

a first resin film;

a first wiring film, a bottom face of which is embedded into the first resin film;

a second wiring film, a bottom face of which is in contact with a surface of the first resin film;

a second resin film formed on a surface of the first wiring film and a surface of the second wiring film, and

at least one first opening is formed in a part of the second resin film where the first wiring film is disposed,

at least one second opening is formed in a part of the second resin film where the second wiring board comprises a base film, and a wire on the base film,

wherein a face of the second flexible wiring board at a side where the wire is disposed is located toward a face of the first flexible wiring board at a side where the second resin film is disposed,

a first bump is arranged in the first opening,

the wire of the second flexible wiring board is connected to the first wiring film by the first bump,

a second bump is arranged in the second opening,

the wire of the second flexible wiring board is connected to the second wiring film by the second bump.

13. A multi-layer flexible wiring board as claimed in claim 12, further comprising:

a third flexible wiring board having a base film, and a wire on the base film,

wherein a face of the third flexible wiring board at a side where the wire is disposed is located toward a face of the first flexible wiring board at a side where the first resin film is disposed,

at least one third opening is formed in a part of the first resin film where the first wiring film is disposed,

a third bump is arranged in the third opening,

the wire of the third flexible wiring board is connected to the first wiring film by the third bump.